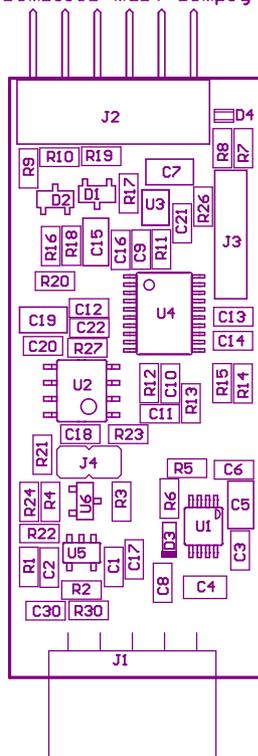


z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

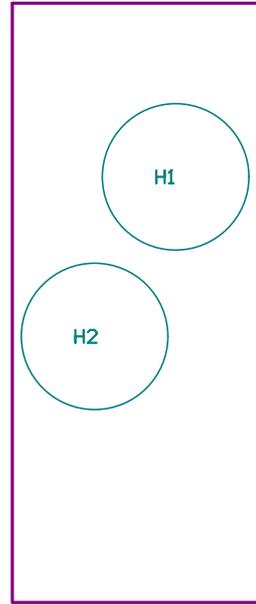
z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00703	REV: E1	SUN REV: Not In VersionControl
M5 Assembly Top	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 12/7/2015	6:16:10 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00703	REV: E1	SUN REV: Not In VersionControl
M6 Assembly Bottom	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/7/2015 6:16:11 PM	TEXAS INSTRUMENTS	

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